Binary Up/Down Counter

The MC14516B synchronous up/down binary counter is constructed with MOS P-channel and N-channel enhancement mode devices in a monolithic structure.

This counter can be preset by applying the desired value, in binary, to the Preset inputs (P0, P1, P2, P3) and then bringing the Preset Enable (PE) high. The direction of counting is controlled by applying a high (for up counting) or a low (for down counting) to the UP/DOWN input. The state of the counter changes on the positive transition of the clock input.

Cascading can be accomplished by connecting the Carry Out to the Carry In of the next stage while clocking each counter in parallel. The outputs (Q0, Q1, Q2, Q3) can be reset to a low state by applying a high to the reset (R) pin.

This CMOS counter finds primary use in up/down and difference counting. Other applications include: (1) Frequency synthesizer applications where low power dissipation and/or high noise immunity is desired, (2) Analog-to-digital and digital-to-analog conversions, and (3) Magnitude and sign generation.

- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Internally Synchronous for High Speed
- Logic Edge–Clocked Design Count Occurs on Positive Going Edge of Clock
- Single Pin Reset
- Asynchronous Preset Enable Operation
- Capable of Driving Two Low–Power TTL Loads or One Low–Power Schottky Load Over the Rated Temperature Range

MAXIMUM RATINGS (Voltages Referenced to V _{SS}) (Note 2.)						
Symbol	Parameter	Value	Unit			
V _{DD}	DC Supply Voltage Range	-0.5 to +18.0	V			
V _{in} , V _{out}	Input or Output Voltage Range (DC or Transient)	-0.5 to V _{DD} + 0.5	V			
I _{in} , I _{out}	Input or Output Current (DC or Transient) per Pin	±10	mA			
PD	Power Dissipation, per Package (Note 3.)	500	mW			
TA	Ambient Temperature Range	-55 to +125	°C			
T _{stg}	Storage Temperature Range	-65 to +150	°C			
TL	Lead Temperature (8–Second Soldering)	260	°C			

MAXIMUM RATINGS (Voltages Referenced to Ves) (Note 2.)

2. Maximum Ratings are those values beyond which damage to the device may occur.

3. Temperature Derating:

Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C



ON Semiconductor

http://onsemi.com

MADIZINIC

		MARKING DIAGRAMS
	PDIP-16 P SUFFIX CASE 648	16 MC14516BCP O AWLYYWW
1.585788881	SOIC-16 D SUFFIX CASE 751B	16 14516B ○ AWLYWW 1
CALLAND AND	SOEIAJ–16 F SUFFIX CASE 966	16 MC14516B AWLYWW 1
A WL or I YY or Y		

YY or Y = Year WW or W = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC14516BCP	PDIP-16	2000/Box
MC14516BD	SOIC-16	48/Rail
MC14516BDR2	SOIC-16	2500/Tape & Reel
MC14516BF	SOEIAJ-16	See Note 1.
MC14516BFEL	SOEIAJ-16	See Note 1.

 For ordering information on the EIAJ version of the SOIC packages, please contact your local ON Semiconductor representative.

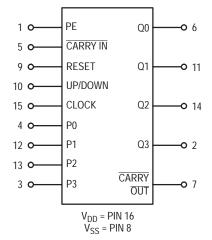
This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}.$

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either $\rm V_{SS}$ or $\rm V_{DD}$). Unused outputs must be left open.

PIN ASSIGNMENT

PE [1•	16] V _{DD}
Q3 [2	15]C
P3 [3	14] Q2
P0 [4	13] P2
CARRY IN	5	12] P1
Q0 [6	11] Q1
CARRY OUT	7	10] U/D
V _{SS} [8	9] R

BLOCK DIAGRAM



TRUTH TABLE

Carry In	Up/Down	Preset Enable	Reset	Clock	Action
1	Х	0	0	Х	No Count
0	1	0	0	7	Count Up
0	0	0	0	7	Count Down
Х	Х	1	0	Х	Preset
Х	Х	Х	1	Х	Reset

X = Don't Care

NOTE: When counting up, the Carry Out signal is normally high and is low only when Q0 through Q3 are high and Carry In is low. When counting down, Carry Out is low only when Q0 through Q3 and Carry In are low.

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

			V _{DD}	- 5	5°C	25°C 125°			5°C		
Characteristic		Symbol	Vdc	Min	Max	Min	Тур ^(4.)	Max	Min	Max	Unit
Output Voltage V _{in} = V _{DD} or 0	"0" Level	V _{OL}	5.0 10 15	_ _ _	0.05 0.05 0.05	_ _ _	0 0 0	0.05 0.05 0.05	_ _ _	0.05 0.05 0.05	Vdc
$V_{in} = 0 \text{ or } V_{DD}$	"1" Level	V _{OH}	5.0 10 15	4.95 9.95 14.95		4.95 9.95 14.95	5.0 10 15		4.95 9.95 14.95		Vdc
Input Voltage $(V_O = 4.5 \text{ or } 0.5 \text{ Vdc})$ $(V_O = 9.0 \text{ or } 1.0 \text{ Vdc})$ $(V_O = 13.5 \text{ or } 1.5 \text{ Vdc})$	"0" Level	V _{IL}	5.0 10 15		1.5 3.0 4.0		2.25 4.50 6.75	1.5 3.0 4.0		1.5 3.0 4.0	Vdc
$(V_{O} = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_{O} = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_{O} = 1.5 \text{ or } 13.5 \text{ Vdc})$	"1" Level	V _{IH}	5.0 10 15	3.5 7.0 11		3.5 7.0 11	2.75 5.50 8.25		3.5 7.0 11		Vdc
Output Drive Current $(V_{OH} = 2.5 \text{ Vdc})$ $(V_{OH} = 4.6 \text{ Vdc})$ $(V_{OH} = 9.5 \text{ Vdc})$ $(V_{OH} = 13.5 \text{ Vdc})$	Source	I _{OH}	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	 	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8	 	- 1.7 - 0.36 - 0.9 - 2.4	 	mAdc
(V _{OL} = 0.4 Vdc) (V _{OL} = 0.5 Vdc) (V _{OL} = 1.5 Vdc)	Sink	I _{OL}	5.0 10 15	0.64 1.6 4.2		0.51 1.3 3.4	0.88 2.25 8.8		0.36 0.9 2.4		mAdc
Input Current		l _{in}	15	—	± 0.1	-	±0.00001	± 0.1	—	± 1.0	μAdc
Input Capacitance (V _{in} = 0)		C _{in}	_	-	_	_	5.0	7.5	_	—	pF
Quiescent Current (Per Package)		I _{DD}	5.0 10 15		5.0 10 20		0.005 0.010 0.015	5.0 10 20		150 300 600	μAdc
Total Supply Current ^(5.) ⁽⁶ (Dynamic plus Quiesce Per Package) (C _L = 50 pF on all outp buffers switching)	ent,	ŀŢ	5.0 10 15		-	I _T = (1	.58 μA/kHz) .20 μA/kHz) .70 μA/kHz)	f + I _{DD}	·	<u>.</u>	μAdc

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
The formulas given are for the typical characteristics only at 25°C.
To calculate total supply current at loads other than 50 pF:

 $I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$

where: I_T is in μA (per package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency, and k = 0.001.

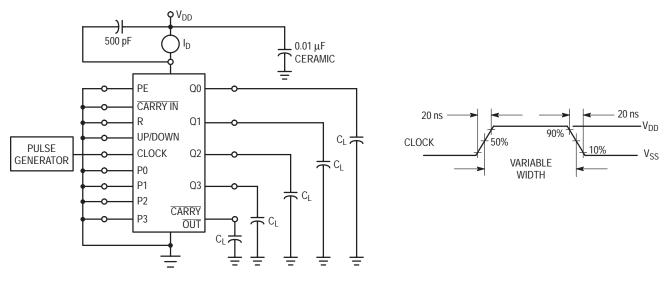
SWITCHING CHARACTERISTICS (7.) ($C_L = 50 \text{ pF}, T_A = 25^{\circ}C$)

				All Types		
Characteristic	Symbol	V _{DD}	Min	Тур ^(8.)	Max	Unit
Output Rise and Fall Time $t_{TLH}, t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ $t_{TLH}, t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$ $t_{TLH}, t_{THL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns}$	t _{TLH} , t _{THL}	5.0 10 15		100 50 40	200 100 80	ns
Propagation Delay Time Clock to Q t_{PLH} , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 230 \text{ ns}$ t_{PLH} , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 97 \text{ ns}$ t_{PLH} , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 75 \text{ ns}$	t _{PLH} , t _{PHL}	5.0 10 15		315 130 100	630 260 200	ns
Clock to Carry Out t_{PLH} , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 230 \text{ ns}$ t_{PLH} , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 97 \text{ ns}$ t_{PLH} , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 75 \text{ ns}$	t _{PLH} , t _{PHL}	5.0 10 15		315 130 100	630 260 200	ns
$\label{eq:carry In to Carry Out} \hline t_{PLH}, t_{PHL} = (1.7 \ \text{ns/pF}) \ \text{C}_{L} + 230 \ \text{ns} \\ t_{PLH}, t_{PHL} = (0.66 \ \text{ns/pF}) \ \text{C}_{L} + 97 \ \text{ns} \\ t_{PLH}, t_{PHL} = (0.5 \ \text{ns/pF}) \ \text{C}_{L} + 75 \ \text{ns} \\ \end{array}$	t _{PLH} , t _{PHL}	5.0 10 15		180 80 60	360 160 120	ns
Preset or Reset to Q t _{PLH} , t _{PHL} = (1.7 ns/pF) C _L + 230 ns t _{PLH} , t _{PHL} = (0.66 ns/pF) C _L + 97 ns t _{PLH} , t _{PHL} = (0.5 ns/pF) C _L + 75 ns	t _{PLH} , t _{PHL}	5.0 10 15	 	315 130 100	630 360 200	ns
Preset or Reset to Carry Out t_{PLH} , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 465 \text{ ns}$ t_{PLH} , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 192 \text{ ns}$ t_{PLH} , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 125 \text{ ns}$	t _{PLH} , t _{PHL}	5.0 10 15		550 225 150	1100 450 300	ns
Reset Pulse Width	t _w	5.0 10 15	380 200 160	190 100 80		ns
Clock Pulse Width	t _{WH}	5.0 10 15	350 170 140	200 100 75		ns
Clock Pulse Frequency	f _{cl}	5.0 10 15		3.0 6.0 8.0	1.5 3.0 4.0	MHz

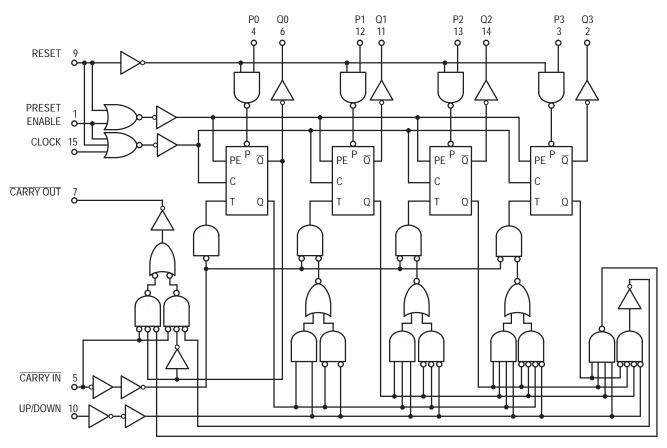
The formulas given are for the typical characteristics only at 25°C.
Data labelled "Typ" is not to be used for design purposes but is intended as an Indication of the IC's potential performance.

			All Types			
Characteristic	Symbol	V _{DD}	Min	Тур (10.)	Max	Unit
Preset or Reset Removal Time The Preset or Reset signal must be low prior to a positive–going transition of the clock.	t _{rem}	5.0 10 15	650 230 180	325 115 90	_	ns
Clock Rise and Fall Time	t _{TLH} , t _{THL}	5.0 10 15			15 5 4	μs
Setup Time Carry In to Clock	t _{su}	5.0 10 15	260 120 100	130 60 50		ns
Hold Time Clock to Carry In	t _h	5.0 10 15	0 20 20	- 60 - 20 0		ns
Setup Time Up/Down to Clock	t _{su}	5.0 10 15	500 200 150	250 100 75		ns
Hold Time Clock to Up/Down	t _h	5.0 10 15	- 70 - 10 0	- 160 - 60 - 40		ns
Setup Time Pn to PE	t _{su}	5.0 10 15	- 40 - 30 - 25	- 120 - 70 - 50		ns
Hold Time PE to Pn	t _h	5.0 10 15	480 420 420	240 210 210		ns
Preset Enable Pulse Width	t _{WH}	5.0 10 15	200 100 80	100 50 40		ns

The formulas given are for the typical characteristics only at 25°C.
Data labelled "Typ" is not to be used for design purposes but is intended as an Indication of the IC's potential performance.

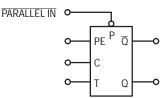






LOGIC DIAGRAM

TOGGLE FLIP-FLOP



FLIP-FLOP FUNCTIONAL TRUTH TABLE

Preset Enable	Clock	т	Q _{n+1}
1	Х	Х	Parallel In
0		0	Q _n
0	7	1	<u>Q</u> n
0	~	Х	Q _n

X = Don't Care

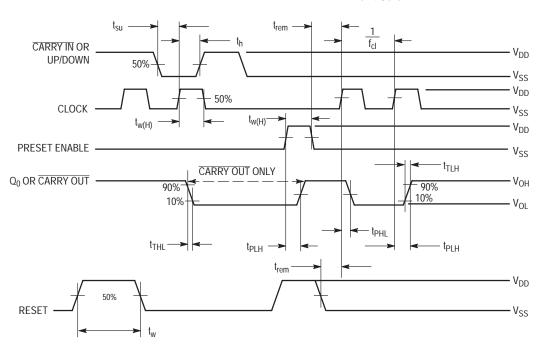


Figure 2. Switching Time Waveforms

PIN DESCRIPTIONS

INPUTS

P0, **P1**, **P2**, **P3**, **Preset Inputs** (**Pins 4**, **12**, **13**, **3**) — Data on these inputs is loaded into the counter when PE is taken high.

 $\overline{\text{Carry In}}$, (Pin 5) — This active–low input is used when Cascading stages. $\overline{\text{Carry In}}$ is usually connected to $\overline{\text{Carry Out}}$ of the previous stage. While high, Clock is inhibited.

Clock, (Pin 15) — Binary data is incremented or decremented, depending on the direction of count, on the positive transition of this input.

OUTPUTS

Q0, Q1, Q2, Q3, Binary outputs (Pins 6, 11, 14, 2) — Binary data is present on these outputs with Q0 corresponding to the least significant bit.

 $\overline{\text{Carry Out}}$, (Pin 7) — Used when cascading stages, $\overline{\text{Carry}}$ $\overline{\text{Out}}$ is usually connected to $\overline{\text{Carry In}}$ of the next stage. This synchronous output is active low and may also be used to indicate terminal count.

CONTROLS

PE, **Preset Enable**, (**Pin 1**) — Asynchronously loads data on the Preset Inputs. This pin is active high and inhibits the clock when high.

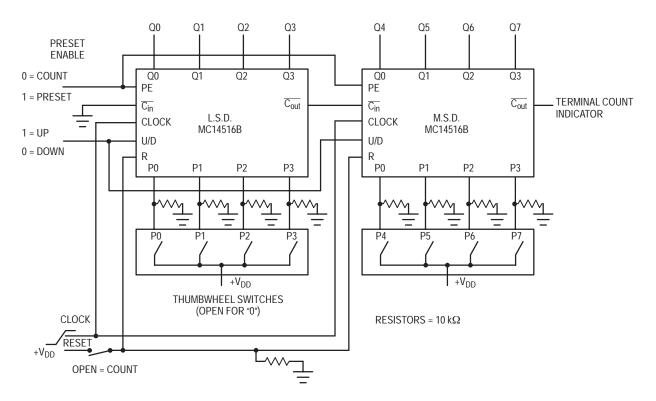
R, **Reset**, (**Pin 9**) — Asynchronously resets the Q outputs to a low state. This pin is active high and inhibits the clock when high.

Up/Down, (Pin 10) — Controls the direction of count, high for up count, low for down count.

SUPPLY PINS

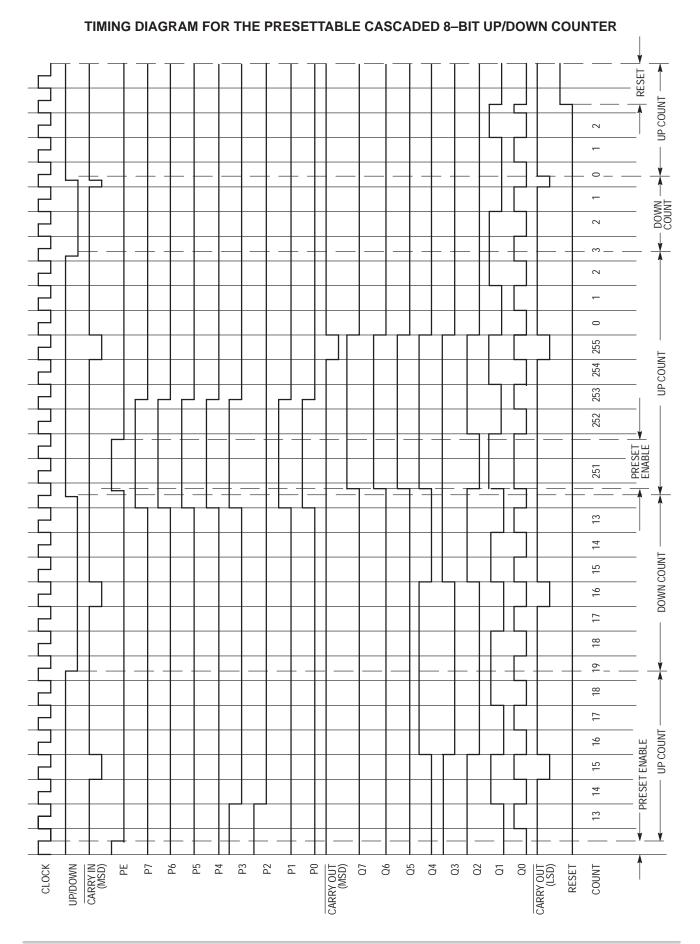
 V_{SS} , Negative Supply Voltage, (Pin 8) — This pin is usually connected to ground.

 V_{DD} , Positive Supply Voltage, (Pin 16) — This pin is connected to a positive supply voltage ranging from 3.0 volts to 18.0 volts.

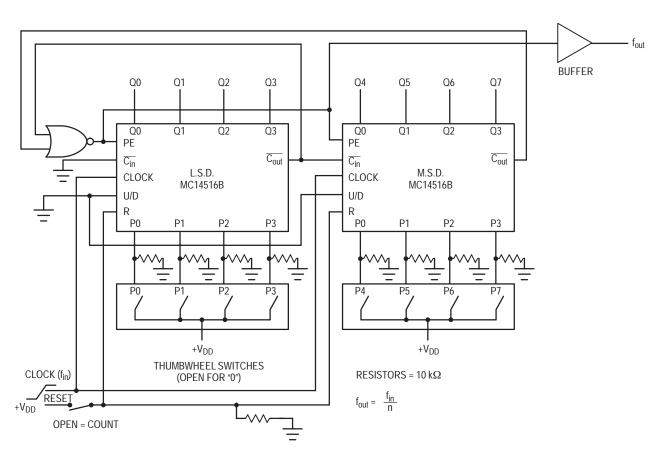


NOTE: The Least Significant Digit (L.S.D.) counts from a preset value once Preset Enable (PE) goes low. The Most Significant Digit (M.S.D.) is disabled while $\overline{C_{in}}$ is high. When the count of the L.S.D. reaches 0 (count down mode) or reaches 15 (count up mode), $\overline{C_{out}}$ goes low for one complete clock cycle, thus allowing the next counter to decrement/increment one count. (See Timing Diagram) The L.S.D. now counts through another cycle (15 clock pulses) and the above cycle is repeated.

Figure 3. Presettable Cascaded 8–Bit Up/Down Counter



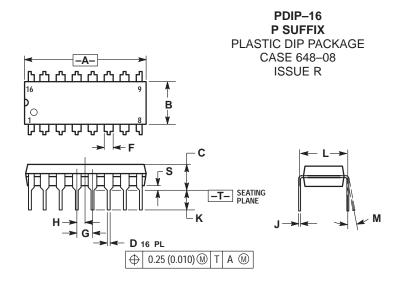
http://onsemi.com 9



NOTE: The programmable frequency divider can be set by applying the desired divide ratio, in binary, to the preset inputs. For example, the maximum divide ratio of 255 may be obtained by applying a 1111 1111 to the preset inputs P0 to P7. For this divide operation, both counters should be configured in the count down mode. The divide ratio of zero is an undefined state and should be avoided.



PACKAGE DIMENSIONS

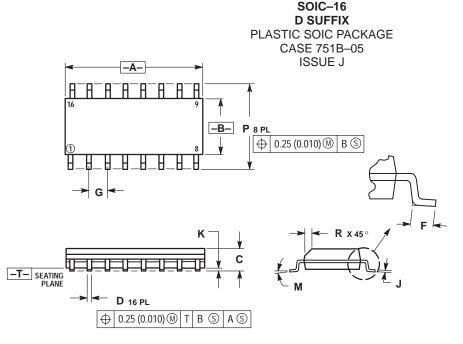


T14.3M, 1992. CONTROLLING DIMENSION: INCH. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL. DIMENSION B DOES NOT INCLUDE MOLD FLASH. ROUNDED CORNERS OPTIONAL. 4. 5. INCHES MILLIMETERS
 DIM
 MIN
 MAX
 MIN
 MAX

 A
 0.740
 0.770
 18.80
 19.55
 B 0.250 0.270 C 0.145 0.175 6.35 6.85 3.69 4.44
 D
 0.015
 0.021

 F
 0.040
 0.70
 0.39 0.53 1.02 1.77 G 0.100 BSC 2.54 BSC Н 0.050 BSC 1.27 BSC 0.008 0.015 0.21 0.38 J K 0.110 0.130 2.80 3.30 L 0.295 0.305 M 0° 10° 7.50 0 ° 7.74 10 ° S 0.020 0.040 0.51 1.01

DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.



NOTES:

NOTES:

2.

3.

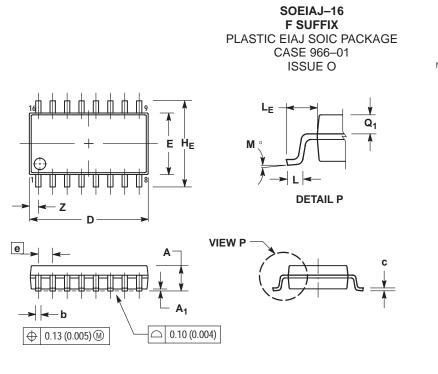
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- 2 3. DIMENSIONS A AND B DO NOT INCLUDE

MOLD PROTRUSION. MAXIMUM MOLD PROTRUSION 0.15 (0.006) 4. PER SIDE. DIMENSION D DOES NOT INCLUDE DAMBAR

5. PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050) BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0 °	7°	0 °	7°
Р	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

PACKAGE DIMENSIONS



NOTES

DIMENSIONING AND TOLERANCING PER ANSI Y14 5M 1982

CONTROLLING DIMENSION: MILLIMETER. B. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE

MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE. . TERMINAL NUMBERS ARE SHOWN FOR

REFERENCE ONLY. THE LEAD WIDTH DIMENSION (b) DOES NOT 5 INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
Ε	5.10	5.45	0.201	0.215
e	1.27	BSC	0.050 BSC	
H _E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
М	0 °	10 °	0 °	10 °
Q ₁	0.70	0.90	0.028	0.035
Ζ		0.78		0.031

are trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes ON Semiconductor and without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and liability including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer.

PUBLICATION ORDERING INFORMATION

NORTH AMERICA Literature Fulfillment:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: ONlit@hibbertco.com Fax Response Line: 303-675-2167 or 800-344-3810 Toll Free USA/Canada

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

EUROPE: LDC for ON Semiconductor - European Support German Phone: (+1) 303-308-7140 (M-F 1:00pm to 5:00pm Munich Time)

Email: ONlit-german@hibbertco.com

- Phone: (+1) 303-308-7141 (M-F 1:00pm to 5:00pm Toulouse Time) French Email: ONlit-french@hibbertco.com
- Phone: (+1) 303-308-7142 (M-F 12:00pm to 5:00pm UK Time) English Email: ONlit@hibbertco.com

EUROPEAN TOLL-FREE ACCESS*: 00-800-4422-3781 *Available from Germany, France, Italy, England, Ireland

CENTRAL/SOUTH AMERICA:

Spanish Phone: 303–308–7143 (Mon–Fri 8:00am to 5:00pm MST) Email: ONlit-spanish@hibbertco.com

ASIA/PACIFIC: LDC for ON Semiconductor - Asia Support Phone: 303-675-2121 (Tue-Fri 9:00am to 1:00pm, Hong Kong Time) Toll Free from Hong Kong & Singapore: 001-800-4422-3781 Email: ONlit-asia@hibbertco.com

JAPAN: ON Semiconductor, Japan Customer Focus Center 4-32-1 Nishi-Gotanda, Shinagawa-ku, Tokyo, Japan 141-8549 Phone: 81-3-5740-2745 Email: r14525@onsemi.com

ON Semiconductor Website: http://onsemi.com

For additional information, please contact your local Sales Representative.